MA3J7440G

Silicon epitaxial planar type

For super high speed switching For small current rectification

■ Features

- High-density mounting is possible
- Forward current (Average) $I_{F(AV)} = 200 \text{ mA}$ rectification is possible

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V _{RRM}	30	V
Forward current (Average)	I _{F(AV)}	200	mA
Peak forward current	I_{FM}	300	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
surge current			
Junction temperature	T _j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: t = 1 s

Package

- Code SMini3-F2
- Pin Name
 - 1: Anode
 - 2: N.C.
- 3: Cathode
- Marking Symbol: M1M

■ Internal Connection

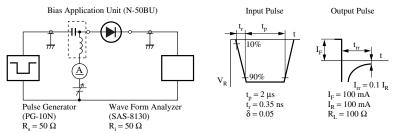


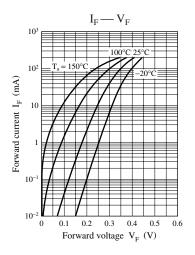
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

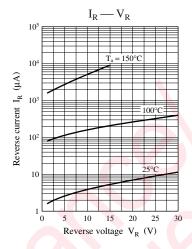
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 200 \text{ mA}$	190		0.55	V
Reverse current	I_R	$V_R = 30 \text{ V}$			50	μΑ
Terminal capacitance	C_{t}	$V_R = 0 V, f = 1 MHz$		30		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		3.0		ns
		$I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$				

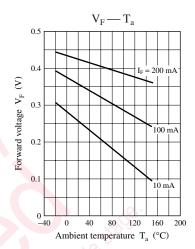
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

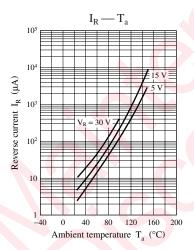
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 2 GHz.
- 4. *: t_{rr} measurement circuit

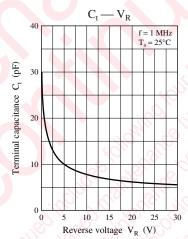


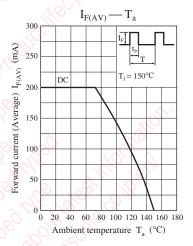






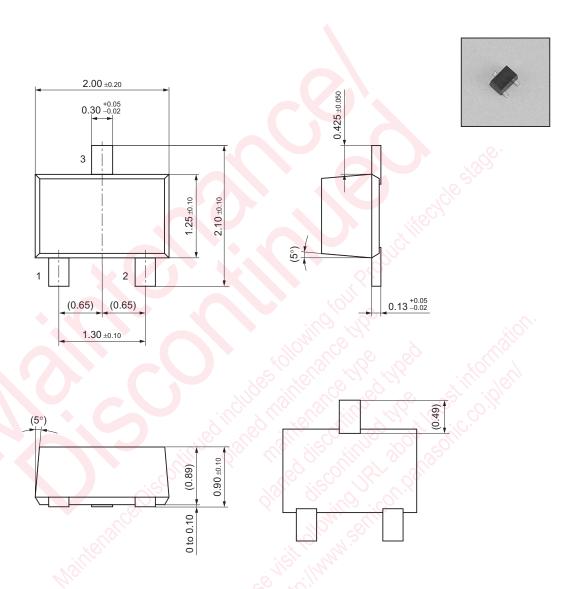






2 SKH00198BED

SMini3-F2 Unit: mm



SKH00198BED 3

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